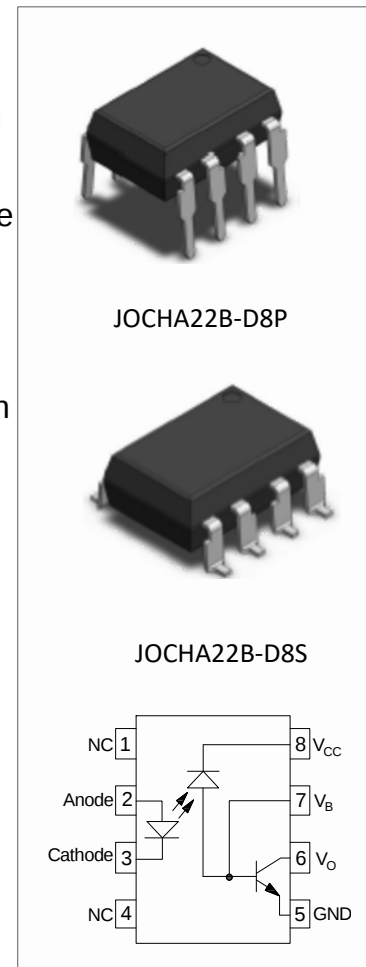


The products are 2MBd high-speed opto-couplers. The device is a small-outline coupler suitable for surface-mount assembly. It consists of a high-output-power infrared LED optically coupled to a high-speed photodiode-transistor chip. It is housed in a plastic DIP8 package with different lead forming options package and guarantees a creepage distance of ≥ 5 mm, a clearance of ≥ 5 mm and an insulation thickness of ≥ 0.4 mm. Therefore, it meets the reinforced insulation class requirements of international safety standards. The products are widely used in programmable controllers, industrial inverters and switching power supplies.

High isolation 5000 VRMS
 High speed – 2MBd typical
 Operating temperature range -40°C to 110°C
 REACH & RoHS compliance
 HBM: H3A; MM: M4; CDM: C3
 CQC approved
 VDE approved
 UL approved



LED	Output
ON	L
OFF	H

(Temperature=25°C)

Input	Forward Current	I _F	50	mA
	Peak Forward Current	I _{FP}	1 ⁷	A
	Reverse Voltage	V _R	6	V
	Input Power Dissipation	P _D	100	mW



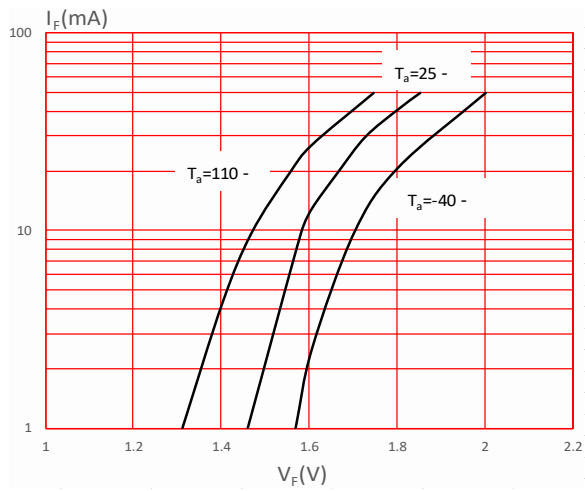
Switching Characteristics	LED Trigger Current	I_{FT}	$I_O=0.75mA$, $V_O \varnothing 0.8V$	-	-	5	mA
	Propagation Delay Time to Logic Low	TPHL	$I_F=0$ 10mA, $R_L=20k\Omega$, $C_L=100pF$	30	150	400	ns
			$I_F=0$ 10mA, $R_L=20k\Omega$, $C_L=10pF$	-	70	-	ns
	Propagation Delay Time to Logic High	TPLH	$I_F=10$ 0mA, $R_L=20k\Omega$, $C_L=100pF$	150	350	550	ns
			$I_F=10$ 0mA, $R_L=20k\Omega$, $C_L=10pF$	-	110	-	ns
	Common Mode Transient Immunity at Logic High	CM_H	$I_F=0mA$, $V_{CM}=1500V_{pp}$, $R_L=20k\Omega$	± 20	± 25	-	kV/ μs
	Common Mode Transient Immunity at Logic Low	CM_L	$I_F=10mA$, $V_{CM}=1500V_{pp}$, $R_L=20k\Omega$	± 20	± 25	-	kV/ μs



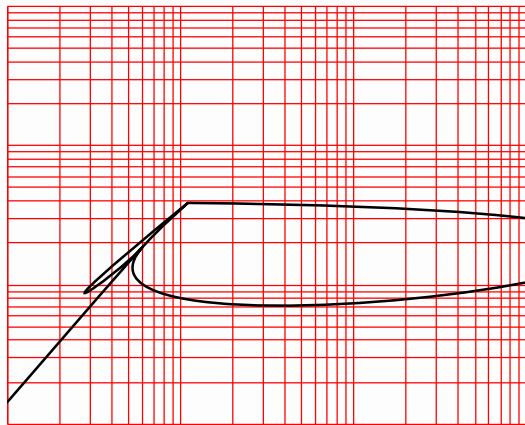
J OC H A 2 2 B -D8P/S /



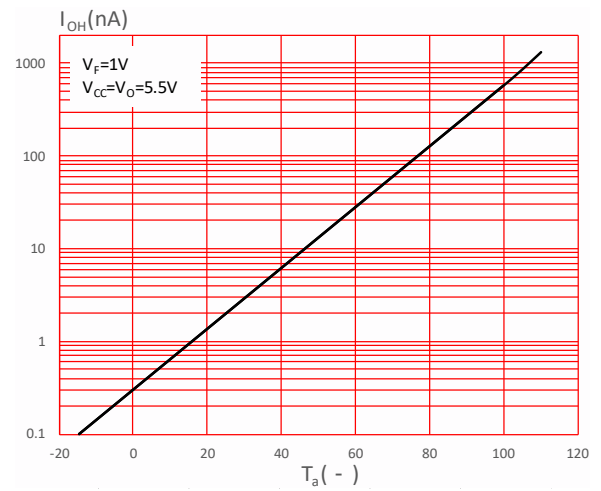
Forward Current vs. Forward Voltage



Output Current vs. Forward Current

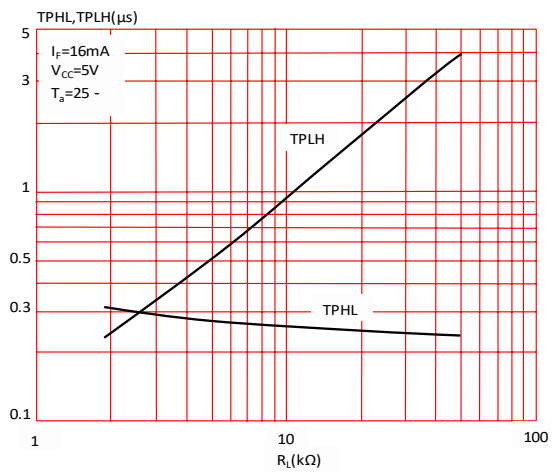


High Level Output Current vs. Ambient Temperature



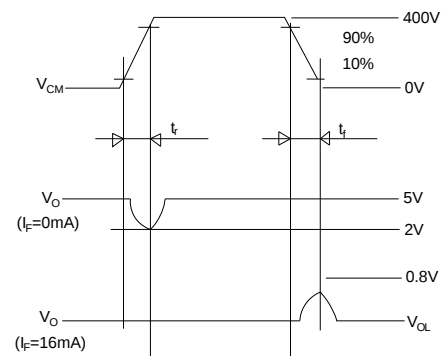
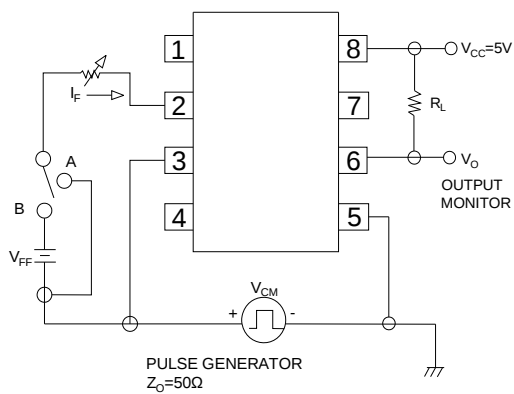
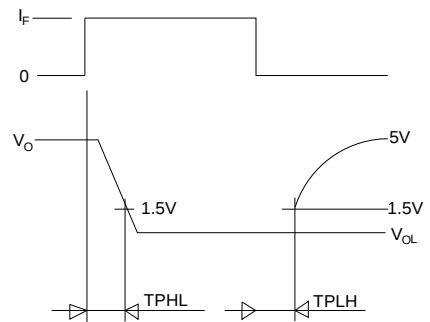
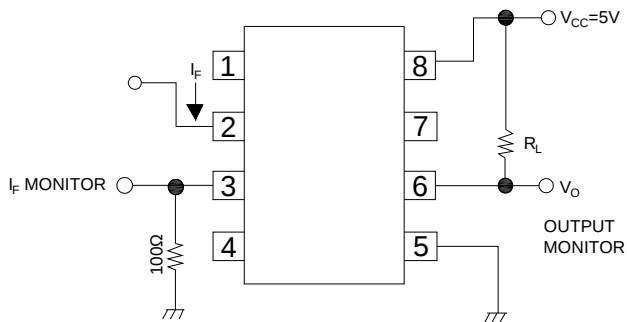
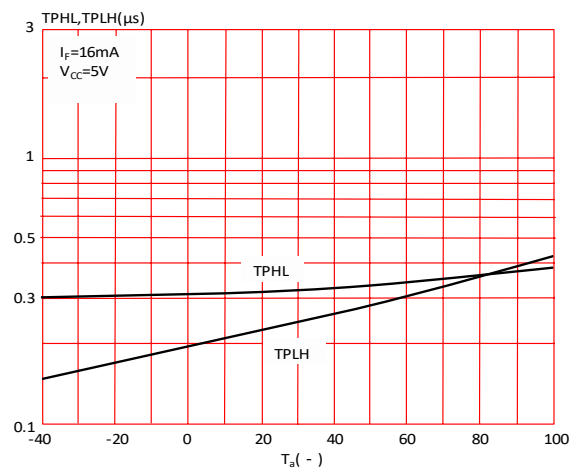
Threshold Input Current vs. Ambient Temperature

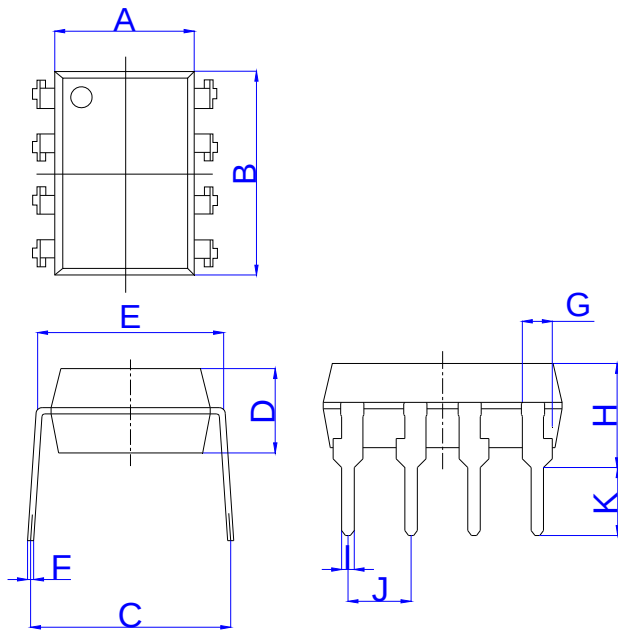
Propagation Delay vs. Load Resistance



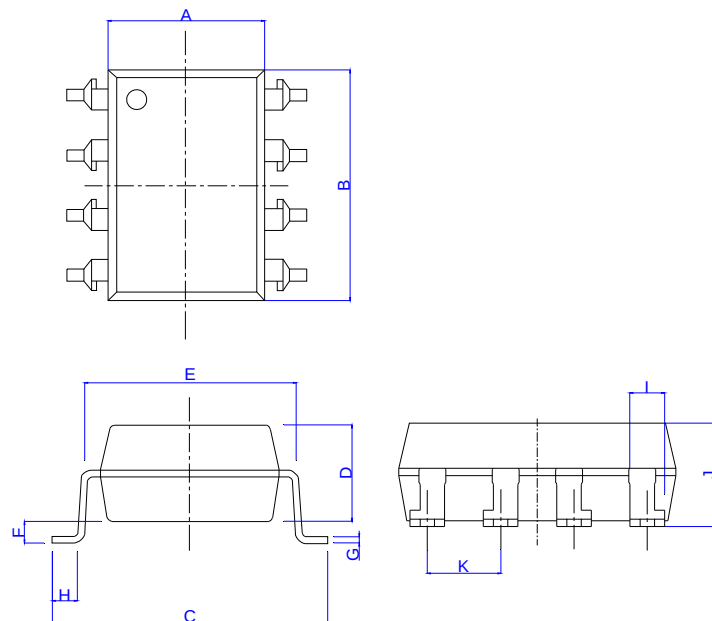
Propagation Delay vs. Ambient Temperature

Temperature

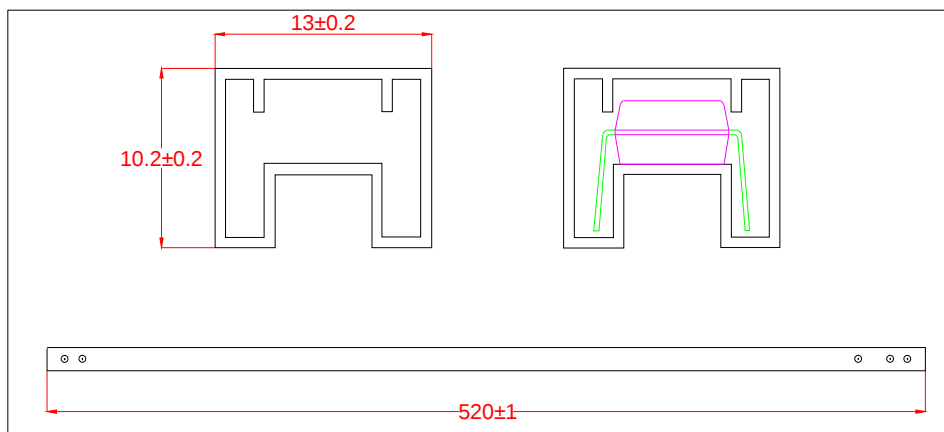
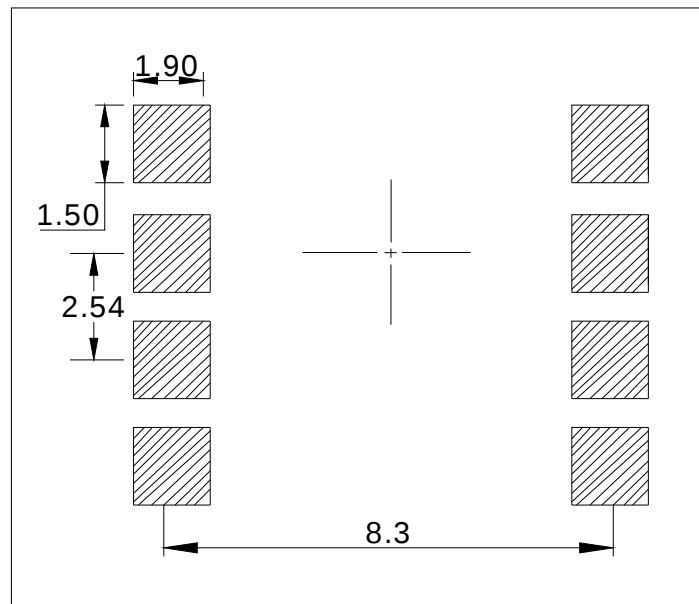


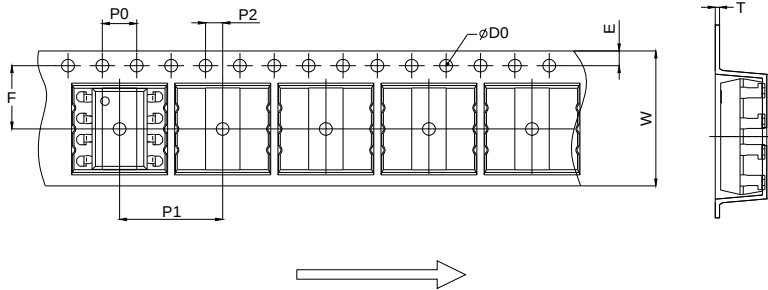


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.60	0.244		0.260
B	9.40		9.80	0.370		0.386
C	7.15		8.95	0.281		0.352
D	3.20		3.60	0.126		0.142
E	7.32		7.92	0.288		0.312
F	0.15		0.35	0.006		0.014
G	0.90		1.50	0.035		0.059
H	3.90		4.50	0.154		0.177
I	0.40		0.60	0.016		0.024
J	2.29		2.79	0.090		0.110
K	2.24		3.24	0.088		0.128

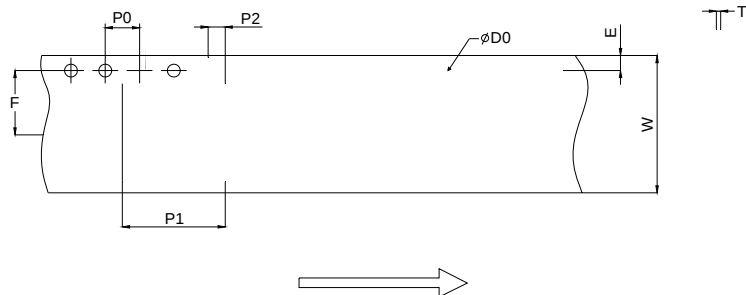


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.60	0.244		0.260
B	9.40		9.80	0.370		0.386
C	9.50		10.50	0.374		0.413
D	3.20		3.60	0.126		0.142
E	7.32		7.92	0.288		0.312
F	0.05		0.35	0.002		0.014
G	0.16		0.36	0.006		0.014
H	0.60		1.40	0.024		0.055
I	0.90		1.50	0.035		0.059
J	3.30		3.90	0.130		0.154
K	2.29		2.79	0.090		0.110

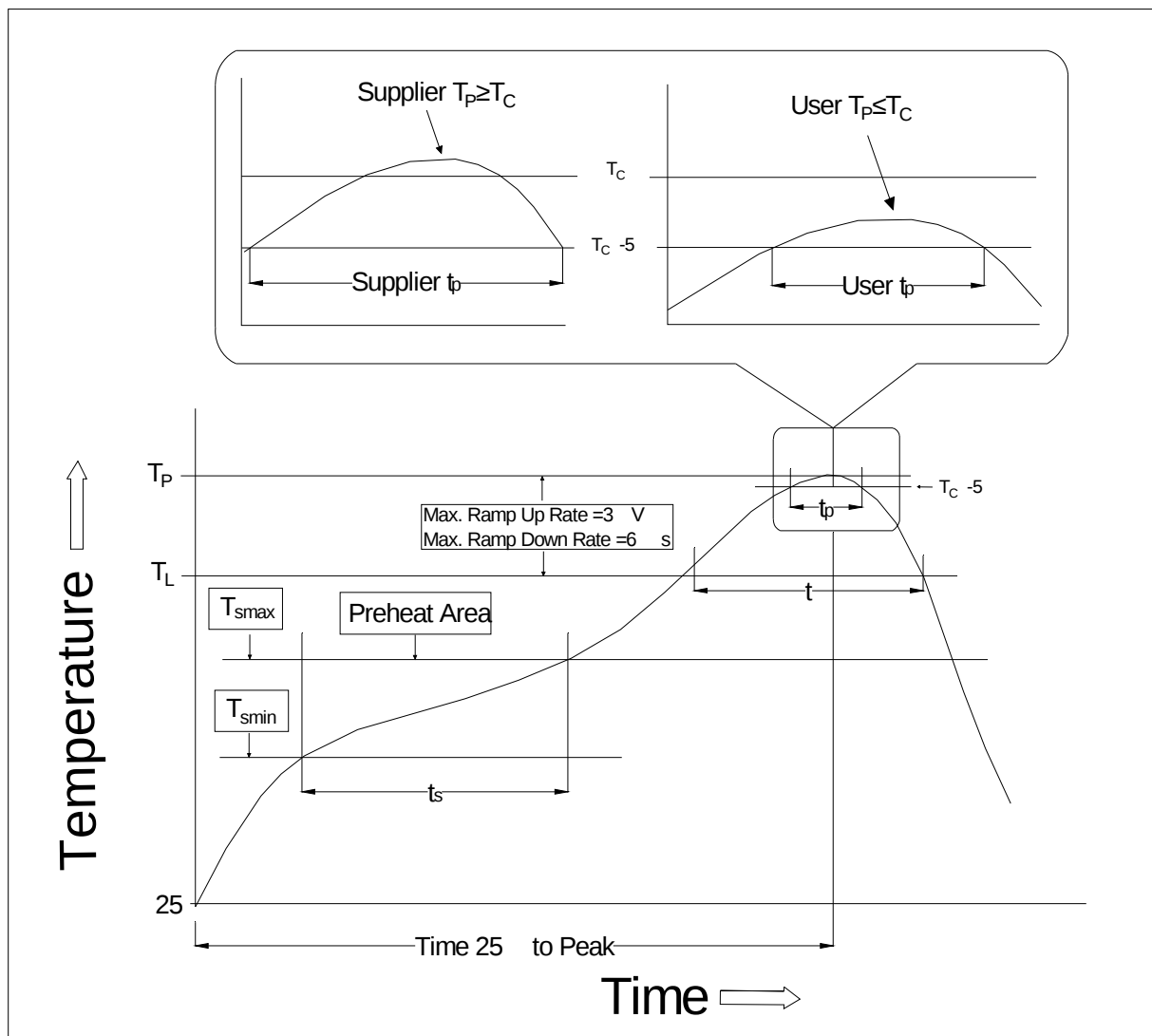




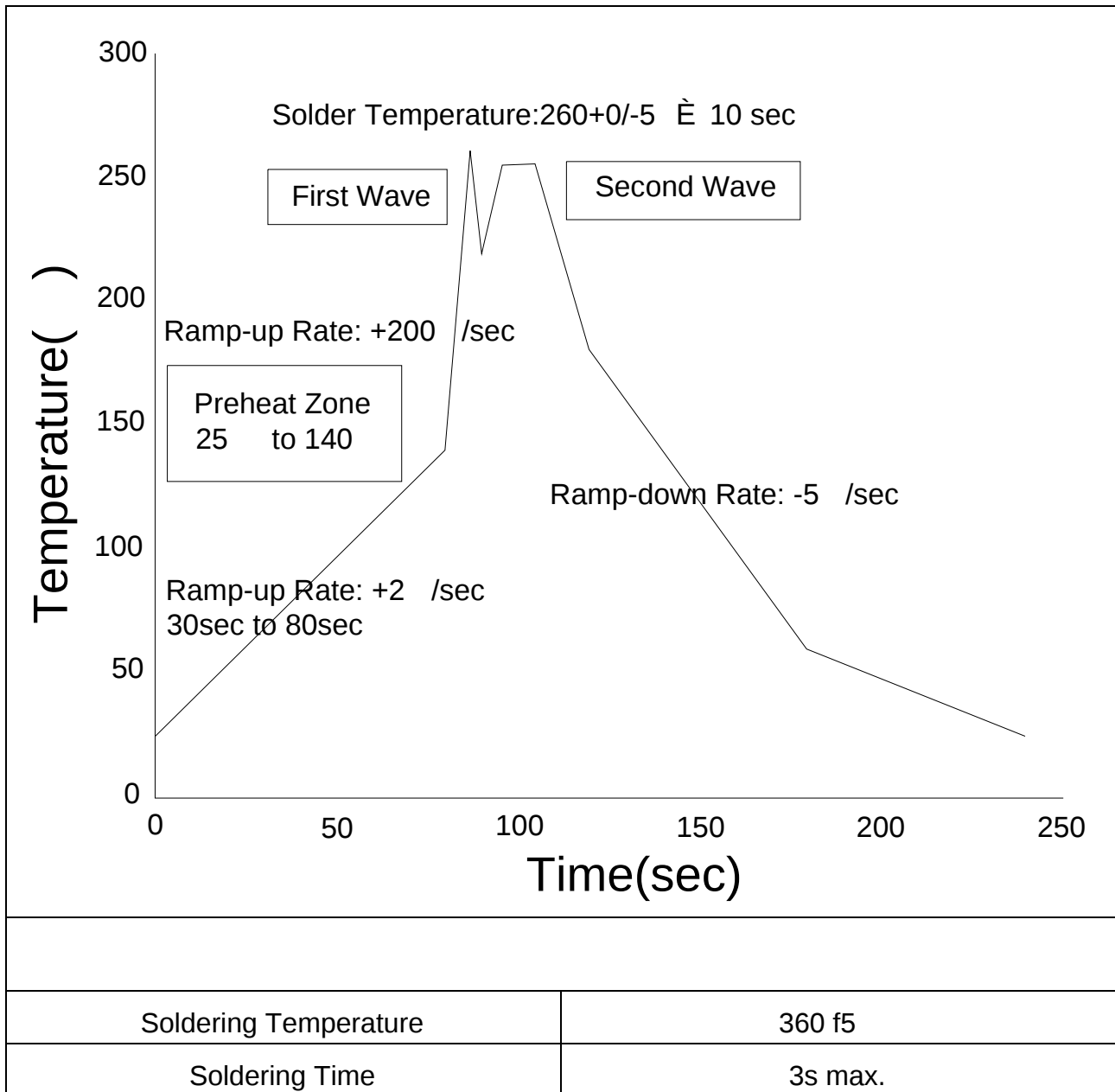
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	11.90	12.00	12.10	0.469	0.472	0.476
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.35	0.40	0.45	0.014	0.016	0.018
W	15.90	16.00	16.20	0.626	0.630	0.638



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	11.90	12.00	12.10	0.469	0.472	0.476
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.35	0.40	0.45	0.014	0.016	0.018
W	15.90	16.00	16.20	0.626	0.630	0.638



Temperature Min. (T_{smin})	100	150
Temperature Max. (T_{smax})	150	200
Time (t_s) from (T_{smin} to T_{smax})	60-120 seconds	60-120 seconds
Ramp-up Rate (t_L to t_P)	3 /second max.	3 /second max.
Liquidus Temperature (T_L)	183	217
Time (t_L) Maintained Above (T_L)	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235 +0 /-5	260 +0 /-5
Time (t_P) within 5 of 260	10 seconds	10 seconds
Ramp-down Rate (T_P to T_L)	3-6 /second	3-6 /second
Time 25 to Peak Temperature	6 minutes max.	8 minutes max.





Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.
2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.
3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.
4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.
5. The component has a shelf life of one year when stored under standard conditions.
6. Recommend storage Temp.: 0~40°C;
Recommend storage humidity: <60%;
MSL level: MSL 1

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